Preferred Device

SWITCHMODE [™] **Power Rectifier**

These state-of-the-art devices are designed for power factor correction in discontinuous and critical conduction mode.

Features

- 520 V Rating Meets 80% Derating Requirements of Major OEMs
- Low Forward Voltage Drop
- Low Leakage
- Ultrafast 95 Nanosecond Recovery Time
- Reduces Forward Conduction Loss
- These are Pb-Free Devices*

Applications

- DCM PFC Designs
- Switching Power Supplies
- Power Inverters

Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 1.1 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	520	V
Average Rectified Forward Current (Rated V_R , $T_C = 65^{\circ}C$)	I _{F(AV)}	4.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, 60 Hz)	I _{FSM}	85	A
Operating Junction Temperature Range	TJ	-65 to +175	°C
Storage Temperature Range	T _{stg}	-65 to +175	°C
ESD Ratings: Machine Model = C Human Body Model = 3B	ESD	> 400 > 8000	٧

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	See Note 2	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



ON Semiconductor®

http://onsemi.com

ULTRAFAST RECTIFIER4.0 AMPERES, 520 VOLTS





AXIAL LEAD CASE 267 STYLE 1

MARKING DIAGRAM



A = Assembly Location

MUR450 = Device Number

YY = Year
WW = Work Week
Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MUR450PF	Axial Lead**	500 Units/Bag
MUR450PFG	Axial Lead**	500 Units/Bag
MUR450PFRL	Axial Lead**	1500/Tape & Reel
MUR450PFRLG	Axial Lead**	1500/Tape & Reel

- †For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.
- **This package is inherently Pb-Free.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage Drop (Note 1) ($I_F = 4$ Amps, $T_J = 25$ °C) ($I_F = 4$ Amps, $T_J = 150$ °C)	V _F	1.15 0.98	V
Maximum Instantaneous Reverse Current (Note 1) $(V_R = 520 \text{ V}, T_J = 25^{\circ}\text{C})$ $(V_R = 520 \text{ V}, T_J = 150^{\circ}\text{C})$	I _R	5.0 400	μΑ
Maximum Reverse Recovery Time (I _F = 1 Amp, di/dt = 50 Amps/ μ s, V _R = 30 V, T _J = 25°C)	t _{rr}	95	ns

^{1.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

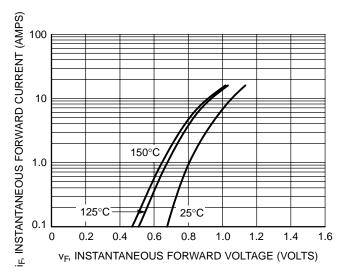


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

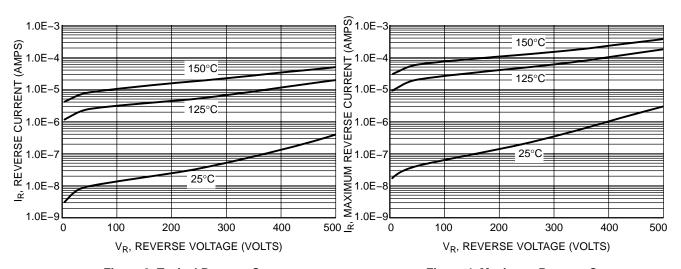


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

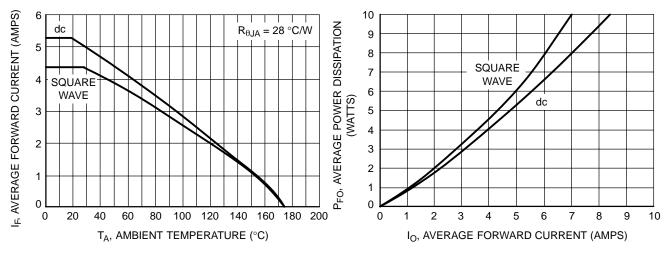


Figure 5. Current Derating

Figure 6. Forward Power Dissipation

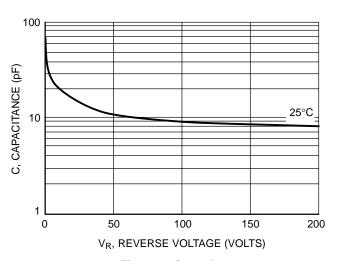


Figure 7. Capacitance

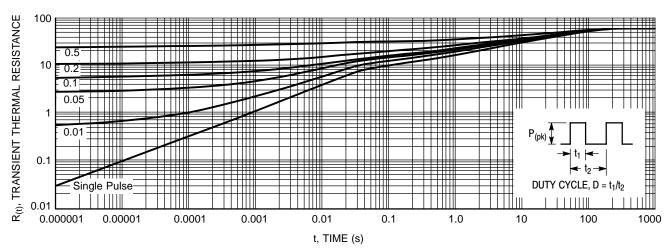


Figure 8. Thermal Response

NOTE 2 — AMBIENT MOUNTING DATA

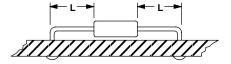
Data shown for thermal resistance, junction—to—ambient $(R_{\theta JA})$ for the mountings shown is to be used as typical guideline values for preliminary engineering or in case the tie point temperature cannot be measured.

TYPICAL VALUES FOR $R_{\theta JA}$ IN STILL AIR

Mounti	ng	Lead Length, L (IN)				
Metho	d	1/8	1/4	1/2	3/4	Units
1		50	51	53	55	°C/W
2	$R_{\theta JA}$	58	59	61	63	°C/W
3		28			°C/W	

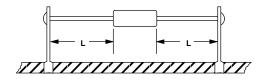
MOUNTING METHOD 1

P.C. Board Where Available Copper Surface area is small.



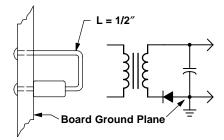
MOUNTING METHOD 2

Vector Push-In Terminals T-28



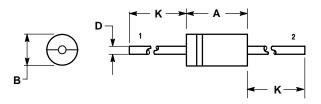
MOUNTING METHOD 3

P.C. Board with 1–1/2" x 1–1/2" Copper Surface



PACKAGE DIMENSIONS

AXIAL LEAD CASE 267-05 (DO-201AD) **ISSUE G**



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.287	0.374	7.30	9.50
В	0.189	0.209	4.80	5.30
D	0.047	0.051	1.20	1.30
K	1.000		25.40	

PIN 1. CATHODE (POLARITY BAND)

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